

General Plating

TABLE- 1 (Tin-Plated)

| Plating Code | Top Plating Thickness | | Under Plating Thickness | | Area | Match Type |
|--------------|-----------------------|--|----------------------------|--|---------|--|
| | | | | | | |
| 1 | 80 μ ” Tin Min. | 112 μ ” Tin Max. (Pre-tinned) | 30 μ Nickel Min. | 50 μ ” Nickel Max. (Pre-tinned) | Overall | Crimp clip terminal |
| | | 128 μ ” Tin Max. (Post Plating) | | 50 μ ” Tin Max. (Post Plating) | | |
| | 100 μ ” Tin Min. | 140 μ ” Tin Max (Pre-tinned) | 30 μ Nickel Min. | 50 μ ” Nickel Max. (Pre-tinned) | Overall | Solder tail terminal & Board in terminal |
| | | 160 μ ” Tin Max (Post Plating) | | 50 μ ” Tin Max. (Post Plating) | | |
| | 120 μ ” Tin Min. | 192 μ ” Tin Max. | 30 μ Nickel Min. | 50 μ Nickel Max. | Overall | Square or round pin |
| | 120 μ ” Tin | 168 μ ” Tin Max (Pre-tinned) | 50 μ Nickel Min. | 70 μ ” Nickel Max. (Pre-tinned) | Overall | SMT type terminal |
| | | 192 μ ” Tin Max (Post Plating) | | 70 μ ” Tin Max. (Post Plating) | | |

TABLE- 2 (Gold -Plated)

| Plating Code | Top Plating Thickness | Under Plating Thickness | | Area | Match Type |
|--------------|-------------------------------------|-------------------------|-------------------|-----------------|------------|
| | | Min. | Max. | | |
| 2 | 0.8 μ ” Gold Min. | 50 μ ” Nickel | 70 μ ” Nickel | Overall | All type |
| 3 | 15 μ ” Gold Min. | 50 μ ” Nickel | 70 μ ” Nickel | Overall | All type |
| 4 | 30 μ ” Gold Min. | 50 μ ” Nickel | 70 μ ” Nickel | Overall | All type |
| A | Selective 1.2 μ ” Gold Flash | 50 μ ” Nickel | | Contact Area | All type |
| B | Selective 15 μ ” Gold | 50 μ ” Nickel | | Contact Area | All type |
| C | Selective 30 μ ” Gold | 50 μ ” Nickel | | Contact Area | All type |
| D | Selective 10 μ ” Gold | 50 μ ” Nickel | | Contact Area | All type |



SOLDERABILITY:

| TEST ITEM | TEST CONDITION | PROCESS | TEST REQUIREMENT |
|----------------|--|-------------------|-------------------------------|
| Solder ability | Soldering time: 5 ± 0.5 Second Soldering pot: $230 \pm 5^\circ\text{C}$ | Sn - Pb Process | Minimum: 95% of immersed area |
| | Soldering time: 3 ± 0.5 Second Soldering pot: $245 \pm 5^\circ\text{C}$ | Lead Free Process | |